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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10016008	FILING DATE 12/11/2001	CLASS 428	SUBCLASS 68	GAU 1772	EXAMINER DFO
**APPLICANTS: Ushiki Takehito; Tsunoda Hitoshi;					
**CONTINUING DATA VERIFIED: THIS APPLICATION IS A DIV OF 09/346,004 07/01/1999 <i>g</i>					
** FOREIGN APPLICATIONS VERIFIED: JAPAN 10-208633 07/08/1998 <i>g</i>					
PG-PUB	DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>	ATTORNEY DOCKET NO	
Foreign priority claimed 35 USC 119 conditions met			<input type="checkbox"/> yes <input type="checkbox"/> no <i>g</i>		
Verified and Acknowledged Examiner's initials <i>g</i>					
TITLE : Semiconductor wafer, method for producing the same, and wafer chuck					
U.S. DEPT. OF COMM./PAT. & TM-PTO-436L(Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Drwg.	Fig.s Drwg.	Print Fig.
TERMINAL DISCLAIMER		Primary Examiner		
		PREPARED FOR ISSUE		
		Application Examiner		
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